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(71) Applicant (for all designated States except US): SHOWA DENKO K.K. [JP/JP]; 13-9, Shiba Daimon 1-chome, Minato-ku, Tokyo 105-8518 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): TSUZUKI, Hiroshi [JP/JP]; c/o Showa Titanium Co., LTD., 3-1, Nishinomiyamachi, Toyama-shi, Toyama, 931-8577 (JP); KOGOI, Hisao [JP/JP]; c/o Showa Titanium Co., LTD., 3-1, Nishinomiyamachi, Toyama-shi, Toyama, 931-8577 (JP). TANAKA, Jun [JP/JP]; c/o SHOWA DENKO K.K., 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 1058518 (JP).

(74) Agent: OHIE, Kunihisa; Ohie Patent Office, Selva-Ningyosho 6F, 14-6, Nihonbashi-Ningyocho, 2-chome, Chuo-Ku Tokyo 103-0013 (JP).

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(54) Title: INORGANIC POWDER, RESIN COMPOSITION FILLED WITH THE POWDER AND USE THEREOF

(57) Abstract: The present invention relates to an inorganic powder having a frequency-size distribution with multiple peaks, wherein the peaks are present at least in the particle size regions from 0.2 to 2 µm and from 2 to 63 µm, preferably with the maximum particle size being 63 µm or less, the average particle size being from 4 to 30 µm, and the mode size being from 2 to 35 µm. The inorganic powder of the present invention is useful as a filler for a high thermally conductive member in electronic component-mounted circuit board required to have electrical insulating property and heat radiating performance, in that a heat radiating member comprising the powder can have thermal conductivity, the powder can provide a resin composition having excellent withstand voltage characteristics for forming an insulative composition into a thin film and can be filled in the resin composition at a high density so as to improve heat radiating performance of the resin composition.